

SEMI-AUTOMATED COATING/DEVELOPING PLATFORM

SUSS ECD8

Resist coating or developing platform





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The ECD8 platform is an enhanced tool that opens up a wide range of applications. It is available as coater or developer and can be perfectly customized. The four options range from a semi-automated open-bowl spin coater to a coater with either GYRSET® cover or air barrier plate and a puddle developer tool. Thanks to its versatility the ECD8 is perfect for use in R&D as well as series production.

With the large number of variants and configurations available, substrates from 2" to 200mm as well as square ones up to 6" edge length can be coated or developed on the ECD8. The platform can be equipped with up to two well proven dispense lines and pump configurations for processing resists with viscosities from <1 cps up to 4000 cps.

UNIQUE GYRSET®

As an additional option the GYRSET® rotating cover can be integrated into the ECD8 spin coating module. For various photoresists and applications, the GYRSET® technology enables a wider process window. Furthermore, square substrates and pieces can be coated all the way to the corners with a homogenous resist thickness.

AIR BARRIER PLATE

The air barrier plate is an alternative to the GYRSET® rotating cover. Positioned approximately 20mm above the chuck surface, this static plate is designed to minimize turbulence across the wafer. All standard chucks can be used with this technology. The air barrier plate is particularly suitable for applications with high spin rates.

SOFTWARE

The Linux-based software installed on the ECD8 is characterized by a particular user-friendly graphical user interface. The intuitive icon-based software makes operation of the ECD8 easy.

ECD8 HIGHLIGHTS

- + Available as coater or developer
- + Extensive basic equipment
- + Great application variety
- + Plug-and-play installation



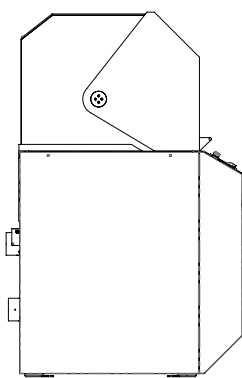
Basic information such as the status of the supply media as well as the current performance values can be checked in real time on the touchscreen monitor. The defined limit values and recipe parameters are monitored, and any deviations that have occurred are subsequently reported.



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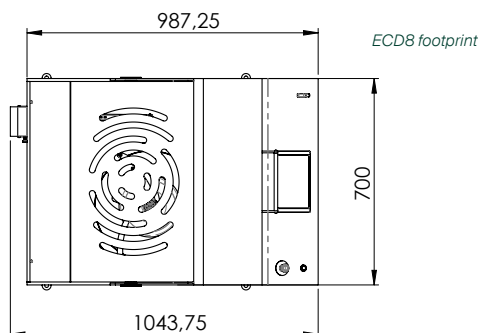
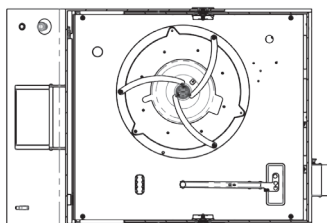
SUSS ECD8

Technical data



ECD8 coater with full enclosure – side view

Process area with one hand centering – top view



ECD8 footprint

GENERAL

Substrate Size	2" to 200 mm round, 2" to 150 mm square
Substrate Handling	Manual
User Interface	Tool control on Linux, industrial PC with touch screen control
Max. # of Recipes	200
Max. # of Process Steps	40
Utilities	230V, 6,5A, 50 Hz/60 Hz

MODULE: OPEN BOWL COATER / AIR BARRIER PLATE

Spin Speed Max	8000 rpm* \pm 1 rpm (with safety hood) at 230V
Spin Acceleration	1–10 000 rpm/s*
Bowl Material	PP-EL-S
Dispense Arm	Dispense arm with up to 2 photoresist lines Up to 2 solvent lines Optional: pneumatic cartridge

MODULE: GYRSET® COATER

Spin Speed Max	4000 rpm* \pm 1 rpm with GYRSET®
Spin Acceleration	1–4000 rpm/s*
Bowl Material	PP-EL-S
Dispense Arm	Dispense arm with up to 2 photoresist lines Up to 2 solvent lines Optional: pneumatic cartridge

MODULE: PUDDLE DEVELOPER

Spin Speed Max	8000 rpm* \pm 1 rpm (with safety hood)
Spin Acceleration	1–10000 rpm/s*
Bowl Material	PP-EL-S

* substrate and chuck dependent

Data, design and specification depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this brochure are not legally binding. SUSS MicroTec reserves the right to change machine specifications without prior notice.



Visit www.suss.com/locations
for your nearest SUSS representative or
contact us:
SUSS MicroTec SE
+49 89 32007-0 · info@suss.com

WWW.SUSS.COM

